US007164192B2

(12) **United States Patent**
Petty-Weeks et al.

(10) **Patent No.: US 7,164,192 B2**
(45) **Date of Patent: Jan. 16, 2007**

(54) **SEMICONDUCTOR DIE PACKAGE WITH REDUCED INDUCTANCE AND REDUCED DIE ATTACH FLOW OUT**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) Appl. No.: **10/364,549**

(22) Filed: **Feb. 10, 2003**

(65) **Prior Publication Data**

US 2004/0155332 A1 Aug. 12, 2004

(51) **Int. Cl.**
H01L 23/495 (2006.01)

(52) **U.S. Cl.** **257/667**; 257/675; 257/E23.037

(58) **Field of Classification Search** 257/686–687, 257/678, 690, 734, 777–778, 784, 667, 410–413, 257/321–322, 336, 344; 438/106–107, 261, 438/287, 216, 585, 586–587, 591, 593, 594, 438/376, 398–399

See application file for complete search history.

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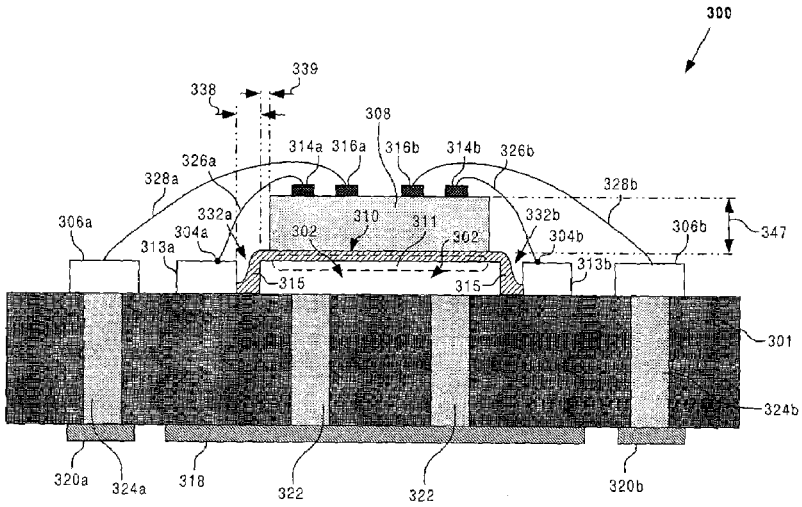
(57) **ABSTRACT**

In one exemplary embodiment, a structure comprises a substrate having a top surface, and a die attach pad situated on the top surface of the substrate. The die attach pad includes a die attach region and at least one substrate ground pad region electrically connected to the die attach region. The die attach pad further includes a die attach stop between the die attach region and the at least one substrate ground pad region. The die attach stop acts to control and limit die attach adhesive flow out to the at least one substrate ground pad region during packaging so that the at least one substrate ground pad region can be moved closer to die attach region so that shorter bond wires for connecting the at least one substrate ground pad region to a die wire bond pad may be used during packaging.

10 Claims, 5 Drawing Sheets